

Organizational Chart

Europe | Japan | North America | China | Korea | Taiwan

**Last Updated: March 2021
v2**

Global Technical Committee (GTC) and Technical Committee (TC) Chapters



Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	3D Packaging & Integration*				TCC		TCC
Automated Test Equipment						TCC	
Automation Technology				TCC			TCC
Compound Semiconductor Materials		TCC	TCC	TCC		TCC	
HB-LED		TCC				TCC	
EH&S				TCC		TCC	TCC
Information & Control				TCC	TCC	TCC	TCC

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., Europe Region)

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles)

*3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017.



Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Facilities			TCC	TCC	TCC	
Gases		TCC	TCC		TCC		
Liquid Chemicals		TCC	TCC		TCC		
FPD Materials & Components			TCC	TCC			
FPD Metrology			TCC	TCC		TCC	
Flexible Hybrid Electronics			TCC			TCC	
MEMS/NEMS					TCC		

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

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Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles)



Global Technical Committee	Locale						
		China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
Metrics				TCC		TCC	
Micropatterning (Microlithography*)						TCC	
Photovoltaic (PV)		TCC		TCC		TCC	TCC
PV Materials		TCC	TCC	TCC		TCC	
Physical Interfaces & Carriers				TCC		TCC	
Silicon Wafer			TCC	TCC		TCC	
Traceability				TCC		TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred to as “a Region” (e.g., Europe Region)

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles)

*In NA, Micropatterning is traditionally called Microlithography.

Regional Standards Committee (RSC) Organizations

SEMI Europe RSC Organization

Co-Chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting
Vice-Chair: Frank Petzold – Trustsec

Europe Chapter of Liquid Chemicals Global Technical Committee

C: Jochen Ruth – Pall Corporation

Europe Chapter of Compound Semiconductor Materials Global Technical Committee

C: Arnd Weber – SiCrystal

Europe Chapter of PV Materials Global Technical Committee

C: Peter Wagner – Consultant

C: Christian Hagendorf – Fraunhofer CSP

Europe Chapter of Gases Global Technical Committee

C: Jochen Ruth – Pall Corporation

Europe Chapter of Silicon Wafer Global Technical Committee

C: Werner Bergholz – International Standards Consulting

C: Peter Wagner – Consultant

C: Fritz Passek - Siltronic



SEMI Japan RSC Organization

Co-Chairs: Takayuki Nishimura – SCREEN Semiconductor Solutions, Tadahiro Furukawa – Yamagata University
Vice-Chair: Supika Mashiro – TEL

**Japan Chapter of
3D Packaging & Integration
Global Technical Committee**
C: Masahiro Tsuriya – iNEMI
C: Haruo Shimamoto – AIST
C: Kazunori Kato – AiT

**Japan Chapter of Facilities
Global Technical Committee**
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

**Japan Chapter of
Information & Control
Global Technical Committee**
C: Takayuki Nishimura – SCREEN
Semiconductor Solutions
C: Mitsuhiro Matsuda – KOKUSAI ELECTRIC

**Japan Chapter of
Physical Interfaces & Carriers
Global Technical Committee**
C: Tsuyoshi Nagashima – Miraial
C: Daisuke Sado – Daihen
C: Yasuhisa Itou – Murata Machinery

**Japan Chapter of
Automation Technology
Global Technical Committee**
C: Terry Asakawa – Vistaideal Consulting
C: Fumiyasu Obuchi – SIEMENS
C: Yasuhiro Kaneko – YAMAHA Motor

**Japan Chapter of
Flexible Hybrid Electronics
Global Technical Committee**
C: Satoshi Maeda – TOYOBO
C: Ryoichi Watanabe – Japan Display
C: Tadahiro Furukawa – Yamagata University

**Japan Chapter of Liquid Chemicals
Global Technical Committee**
C: Hiroshi Tomita – KIOXIA
C: Hiroyuki Araki – SCREEN Semiconductor
Solutions

**Japan Chapter of Silicon Wafer
Global Technical Committee**
C: Tetsuya Nakai – SUMCO
C: Ryuji Takeda – GlobalWafers Japan

**Japan Chapter of
Compound Semiconductor Materials
Global Technical Committee**
C: Masayoshi Obara – Shin-Etsu Handotai

**Japan Chapter of
FPD Materials & Components
Global Technical Committee**
C: Tadahiro Furukawa – Yamagata University
C: Yoshihiko Shibahara – FUJIFILM

**Japan Chapter of Metrics
Global Technical Committee**
C: Mitsune Sakamoto – ZAMA Consulting

**Japan Chapter of Traceability
Global Technical Committee**
C: Yoichi Iga – JEITA
C: Hirokazu Tsunobuchi – Consultant

**Japan Chapter of
Environmental Health & Safety
Global Technical Committee**
C: Supika Mashiro – TEL
C: Hidetoshi Sakura – NuFlare Technology
C: Moray Crawford – Hatsuta Seisakusho

**Japan Chapter of FPD Metrology
Global Technical Committee**
C: Ryoichi Watanabe – Japan Display
C: Akira Kawaguchi – Otsuka Electronics

**Japan Chapter of Photovoltaic
Global Technical Committee**
C: Kazuhiko Kashima – Consultant
C: Masaaki Yamamichi – RTS Corporation

Special Groups
Reporting to the JRSC

**Japan Chapter of Gases
Global Technical Committee**
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

**Japan Chapter of PV Materials
Global Technical Committee**
C: Kazuhiko Kashima – Consultant
C: Tetsuo Fukuda – Nihon University

**Standardization Process
Improvement (SPI)**
L: Supika Mashiro – TEL



SEMI North America (NA) RSC Organization – NA Locale

Co-Chairs: Steve Lewis – Lam Research, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimetrix

<p>NA Chapter of 3D Packaging & Integration Global Technical Committee C: Chris Moore – Covalent Metrology C: Bill Kerr – Evergreen Enhancement</p>	<p>NA Chapter of Gases Global Technical Committee C: Mohamed Saleem – Brooks Instrument</p>	<p>NA Chapter of Metrics Global Technical Committee C: David Bouldin – Fab Consulting C: Mark Frankfurth – Cymer C: Vladimir Kraz – BestESD</p>	<p>NA Chapter of Silicon Wafer Global Technical Committee C: Dinesh Gupta – STA C: Noel Poduje – SMS VC: Mike Goldstein</p>
<p>NA Chapter of Automated Test Equipment Global Technical Committee C: Mark Roos – Roos Instruments C: Stacey Ajouri – Texas Instruments C: Laurent Bonneval – Teradyne</p>	<p>NA Chapter of HB-LED Global Technical Committee C: Mike Feng – Silian C: Chris Moore – Covalent Metrology C: Andrew Kim – InnovationforX</p>	<p>NA Chapter of Microlithography Global Technical Committee C: Bryan Barnes – NIST</p>	<p>NA Chapter of Traceability Global Technical Committee C: Yaw Obeng – NIST C: David Huntley – PDF Solutions</p>
<p>NA Chapter of Compound Semiconductor Materials Global Technical Committee C: Russ Kremer – Consultant C: James Oliver – Northrop Grumman</p>	<p>NA Chapter of Information & Control Global Technical Committee C: Jack Ghiselli – Ghiselli Consulting C: Brian Rubow – Cimetrix C: James Moyne – AMAT/ University of Michigan</p>	<p>NA Chapter of Photovoltaic Global Technical Committee C: James Moyne – AMAT/University of Michigan</p>	<p>NA RSC Technical Architect Board C: James Moyne – AMAT/ University of Michigan C: Yaw Obeng – NIST</p>
<p>NA Chapter of Environmental, Health & Safety Global Technical Committee C: Chris Evanston – Salus Engineering C: Sean Larsen – Lam Research C: Bert Planting – ASML</p>	<p>NA Chapter of Liquid Chemicals Global Technical Committee C: Don Hadder – Intel C: Steve Rogers – KMG Chemicals C: Laura Ledenbach – PeroxyChem Evonik C: Koh Murai – Mega Fluid Systems</p>	<p>NA Chapter of PV Materials Global Technical Committee C: Hugh Gotts – Air Liquide</p>	
<p>NA Chapter of Facilities Global Technical Committee C: Steve Lewis – Lam Research</p>	<p>NA Chapter of MEMS/NEMS Global Technical Committee C: Steve Martell – Nordson SONOSCAN C: Michelle Bourke – Lam Research</p>	<p>NA Chapter of Physical Interfaces & Carriers Global Technical Committee C: Matt Fuller – Entegris C: Melvin Jung – Intel</p>	



SEMI North America RSC Organization

China Locale

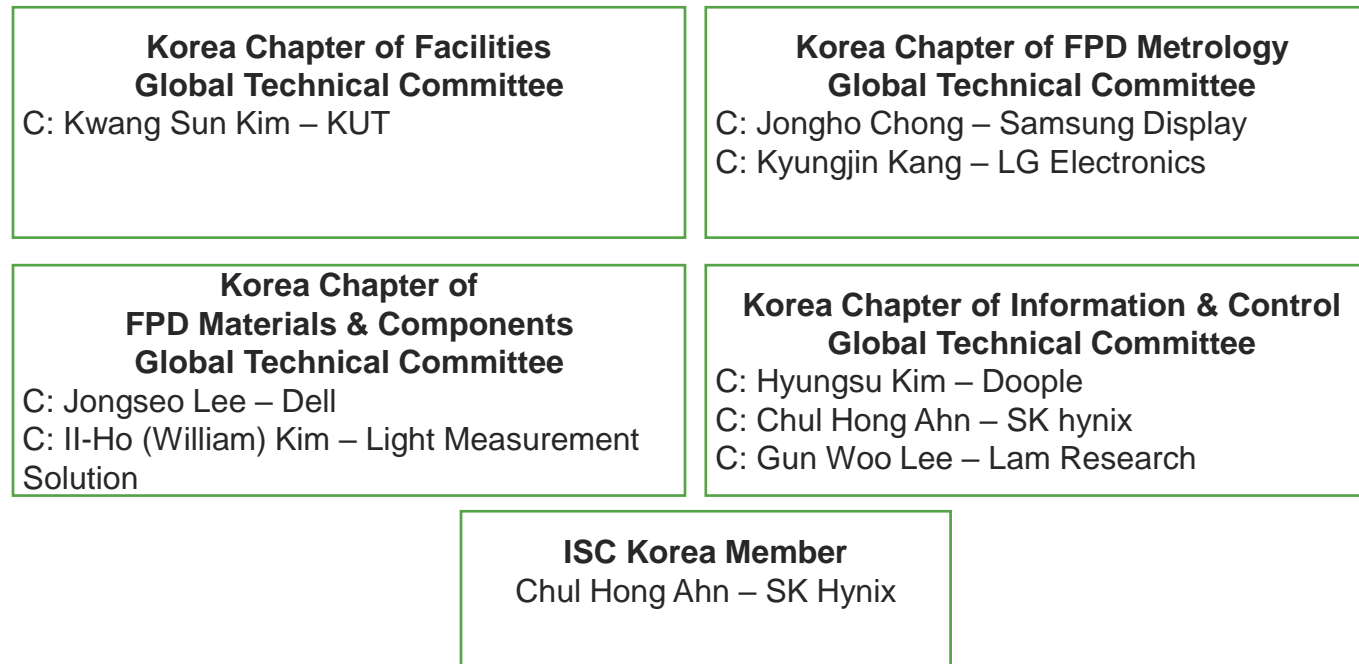
Co-Chairs: Steve Lewis – Lam Research, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimatrix



SEMI North America RSC Organization

Korea Locale

Co-Chairs: Steve Lewis – Lam Research, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimetrix



SEMI North America RSC Organization

Taiwan Locale

Co-Chairs: Steve Lewis – Lam Research, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimetricx

Taiwan Chapter of 3D Packaging & Integration Global Technical Committee

C: Wendy Chen – King Yuan Electronics
C: Wei-Chung Lo – ITRI
C: Roger Hwang – ASE

Taiwan Chapter of FPD Metrology Global Technical Committee

C: Jia-Ming Liu – TDMDA
C: Jen-Chieh Wang – CMS/ITRI

Taiwan Chapter of Information & Control Global Technical Committee

C: Scott Yu – TSMC

Taiwan Chapter of Automation Technology Global Technical Committee

C: K.C. Chou – ASE
C: Jen-Hui Tsai – ITRI
C: Jui-Ming Hua – MIRDC

Taiwan Chapter of Flexible Hybrid Electronics Global Technical Committee

C: Steve Huang – AiQ
C: Y.E. Yeh – ASE

Taiwan Chapter of Photovoltaic Global Technical Committee

C: T.C. Wu – CMS/ITRI
C: Ray Sung – UL Taiwan
C: C.C. Lin – PV Guider

Taiwan Chapter of Environmental Health & Safety Global Technical Committee

C: Shuh-Woei Yu – SAHTECH

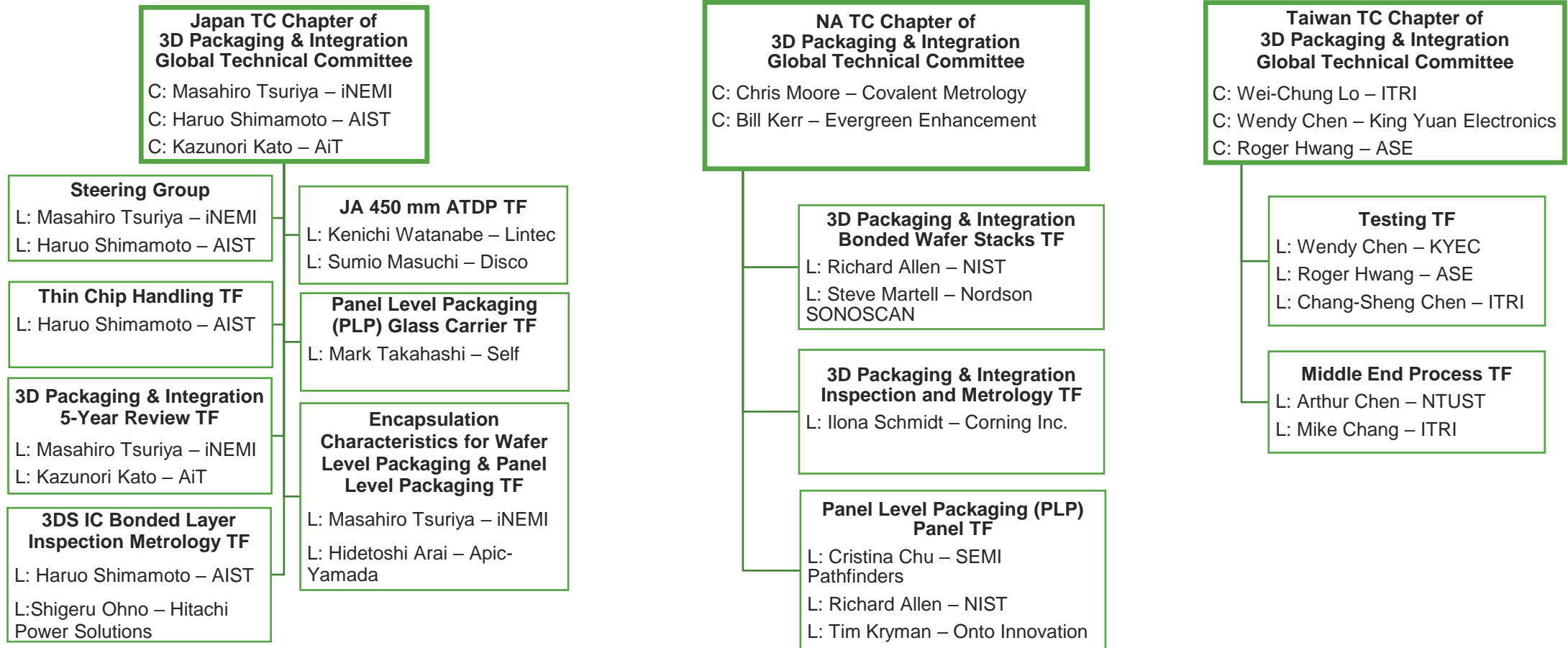
ISC Taiwan Member

Jen-Chieh Wang – CMS/ITR

Organization of Each TC Chapter

TF = Task Force | WG = Working Group

3D Packaging & Integration (3DP&I) Global Technical Committee



Automation Technology (AT) Global Technical Committee



**Japan TC Chapter of
Automation Technology
Global Technical Committee**
C: Terry Asakawa – Vistaideal Consulting
C: Fumiyasu Obuchi – SIEMENS
C: Yasuhiro Kaneko – YAMAHA Motor

A1 TF
L: Ryota Shimono – SIEMENS
L: Takeo Yamaki – Yokogawa Solution
Services

Surface Mount Technology (SMT) TF
L: Jun Isaka – FUJI
L: Takahiko Imasu – JUKI
L: Atsushi Horibe – Panasonic
L: Yasuhiro Kaneko – YAMAHA Motor

F-GEM TF
L: Terry Asakawa – Vistaideal Consulting
L: Takashi Nakagawa – Yokogawa Solution
Services
L: Takahiro Nagatomo – Cimatrix

**Taiwan TC Chapter of
Automation Technology
Global Technical Committee**
C: K.C. Chou – ASE
C: Jen-Hui Tsai – ITRI/MMSRL
C: Jui-Ming Hua – MIRDC

PCBECI TF
L: J.S. Su – ASE
L: Chi-Pin Chen – ITRI
L: Chi-Yuan Chang – Symtek

Automated Test Equipment (ATE) Global Technical Committee

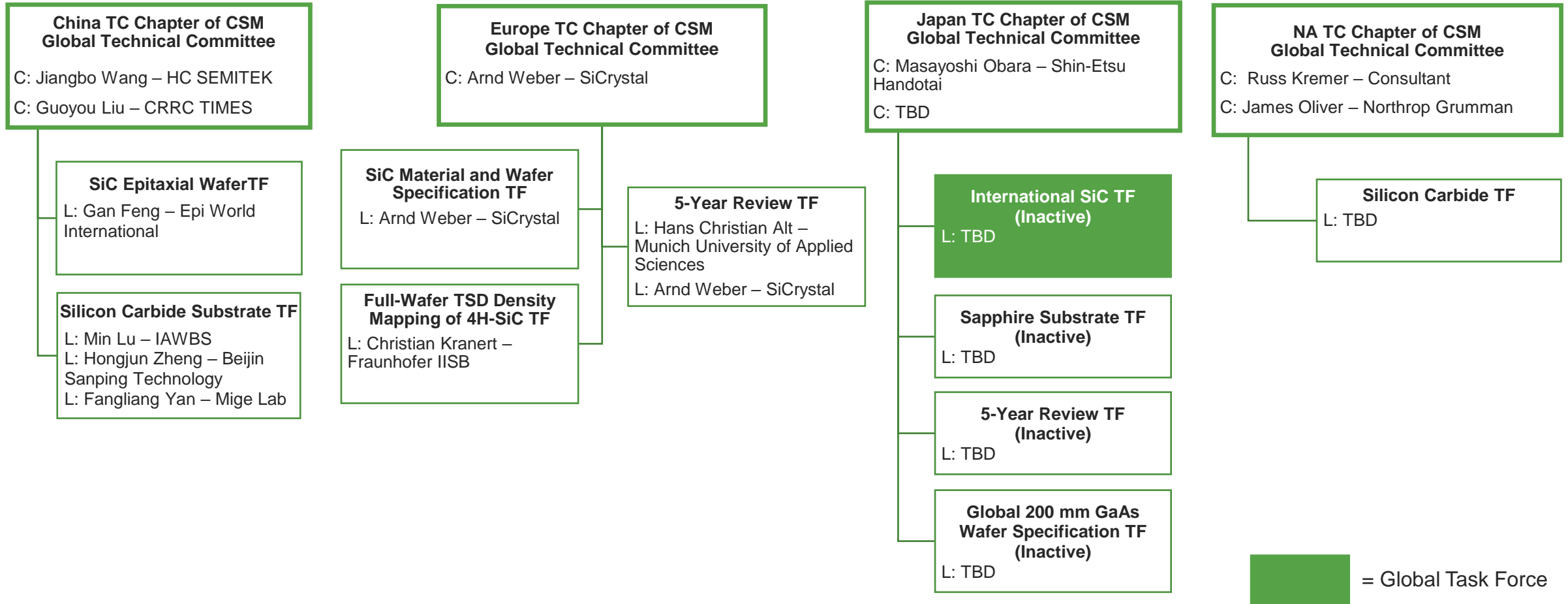


**NA TC Chapter of
Automated Test Equipment
Global Technical Committee**
C: Mark Roos – Roos Instruments
C: Stacey Ajouri – Texas Instruments
C: Laurent Bonneval – Teradyne

Rich Interactive Database (RITdb) TF
L: Mark Roos – Roos Instruments
L: Stacey Ajouri – Texas Instruments

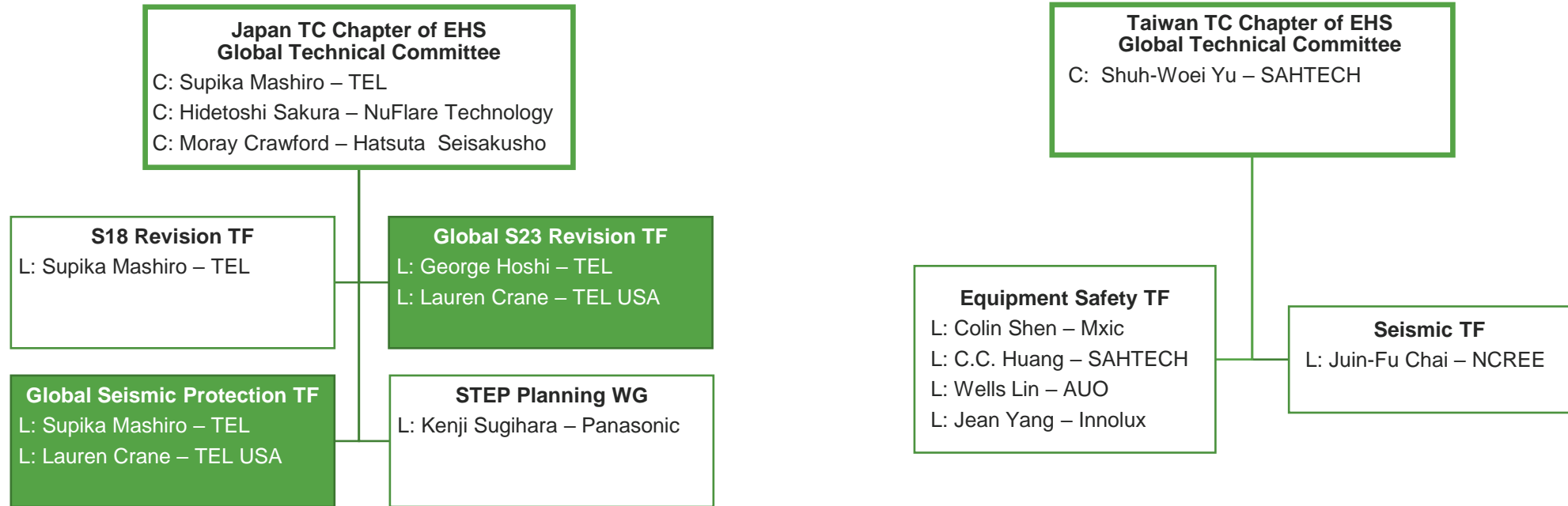
**Tester Event Messaging for
Semiconductors (TEMS) TF**
L: Laurent Bonneval – Teradyne

Compound Semiconductor Materials (CSM) Global Technical Committee



Environmental, Health & Safety (EH&S)

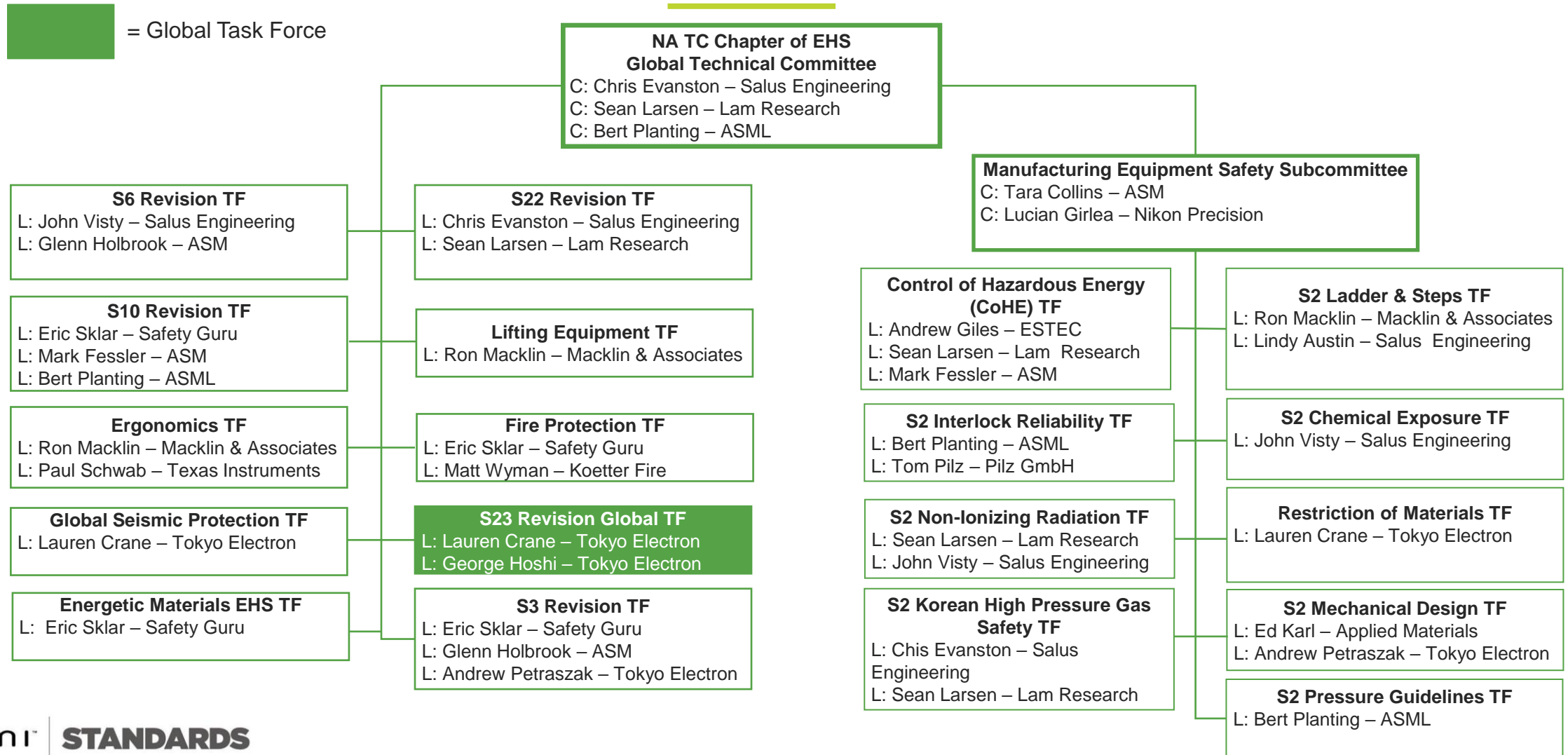
Global Technical Committee



 = Global Task Force

Environmental, Health & Safety (EH&S)

Global Technical Committee



Facilities

Global Technical Committee

**Japan TC Chapter of Facilities
Global Technical Committee**
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

F1 Revision TF
L: Masafumi Kitano – Fujikin
L: Kazuhiko Takamisawa –
NISSAN TANAKA

5-Year Review TF
L: Masafumi Kitano – Fujikin

**NA TC Chapter of Facilities
Global Technical Committee**
C: Steve Lewis – Lam Research

F51 Revision TF
L: Dalia Vernikovsky – Applied
Seals North America

**Building Information Modeling
(BIM) for Semiconductor Capital
Equipment TF**
L: Michael Potts – Exyte

Power Grid Harmonics TF
L: Open

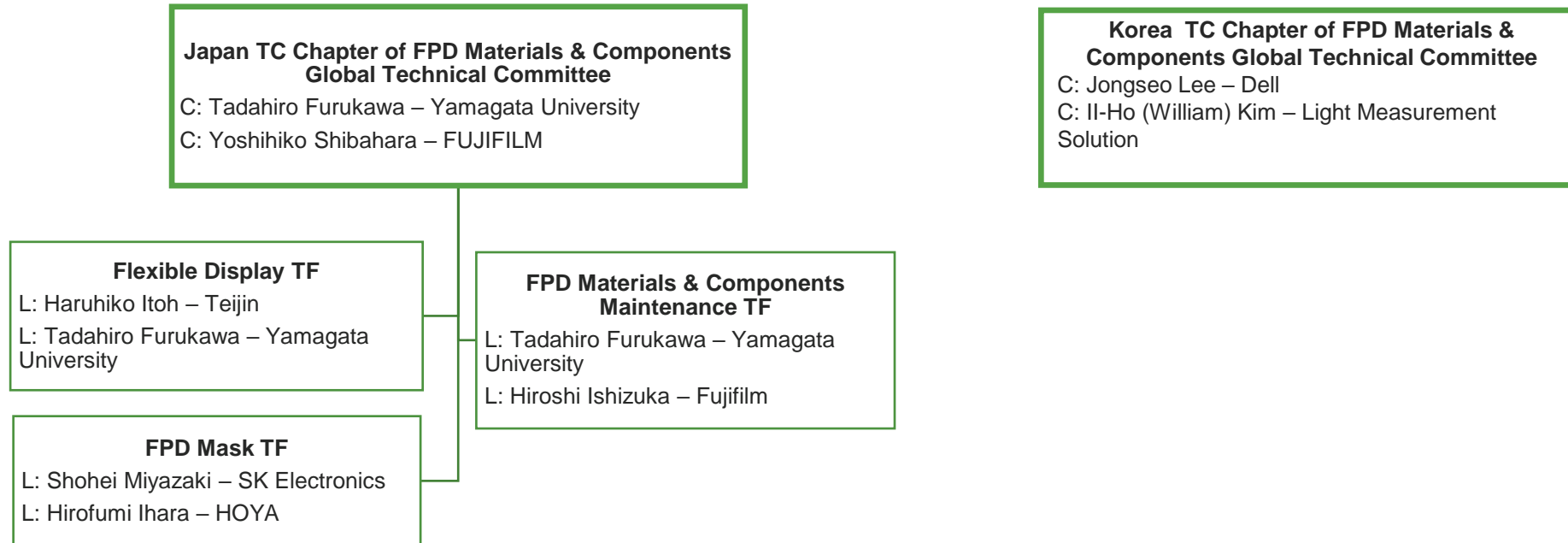
Voltage Sag Immunity TF
L: Mark Stephens – EPRI

**Korea TC Chapter of Facilities
Global Technical Committee**
C: Kwang Sun Kim – KUT

Equipment Cleanness TF
L: TBD

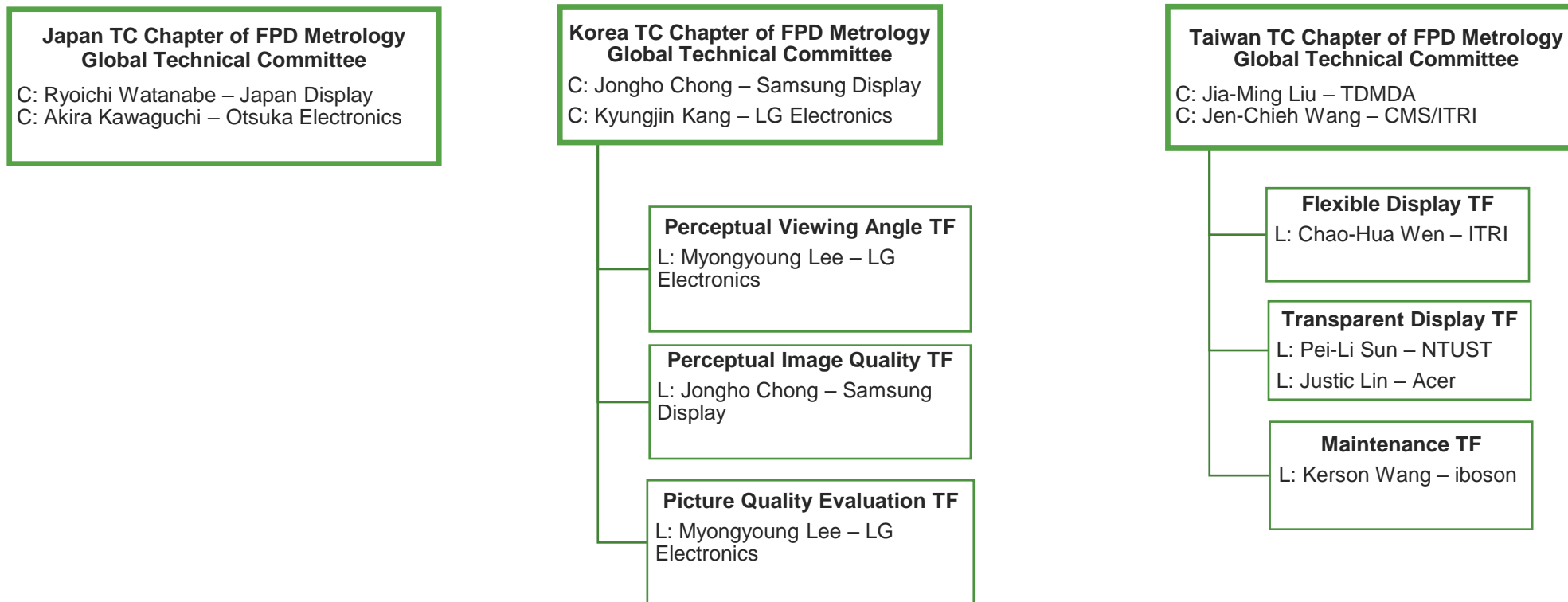


Flat Panel Display (FPD) - Materials & Components Global Technical Committee



FPD Metrology

Global Technical Committee



Flexible Hybrid Electronics (FHE) Global Technical Committee



**Japan TC Chapter of
Flexible Hybrid Electronics
Global Technical Committee**

C: Satoshi Maeda – TOYOBO
C: Ryoichi Watanabe – Japan Display
C: Tadahiro Furukawa – Yamagata University

**Taiwan TC Chapter of
Flexible Hybrid Electronics
Global Technical Committee**

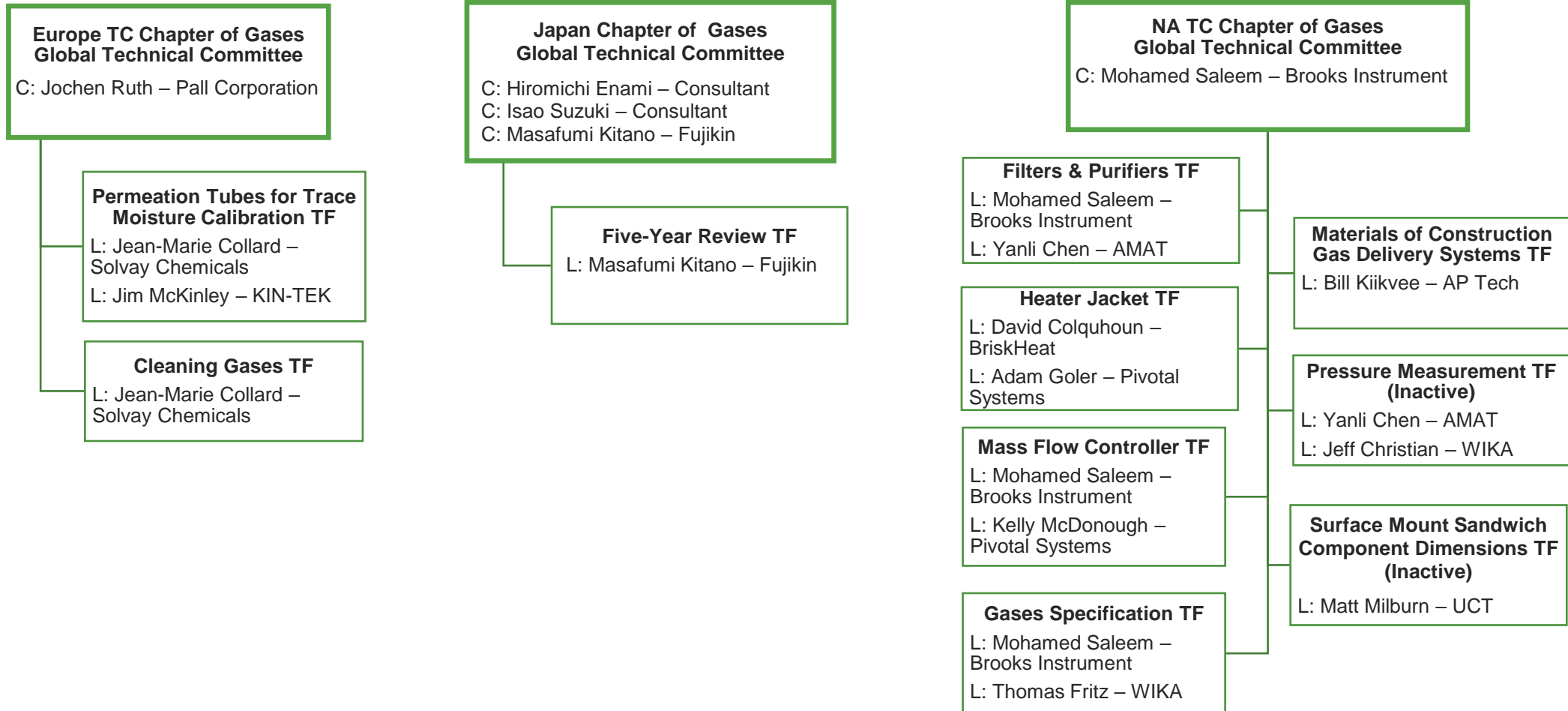
C: Steve Huang – AiQ
C: Y.E. Yeh – ASE

FHE System for Wearable TF

L: Steve Chiu – ITRI
L: Wei-Yuan Cheng – ITRI

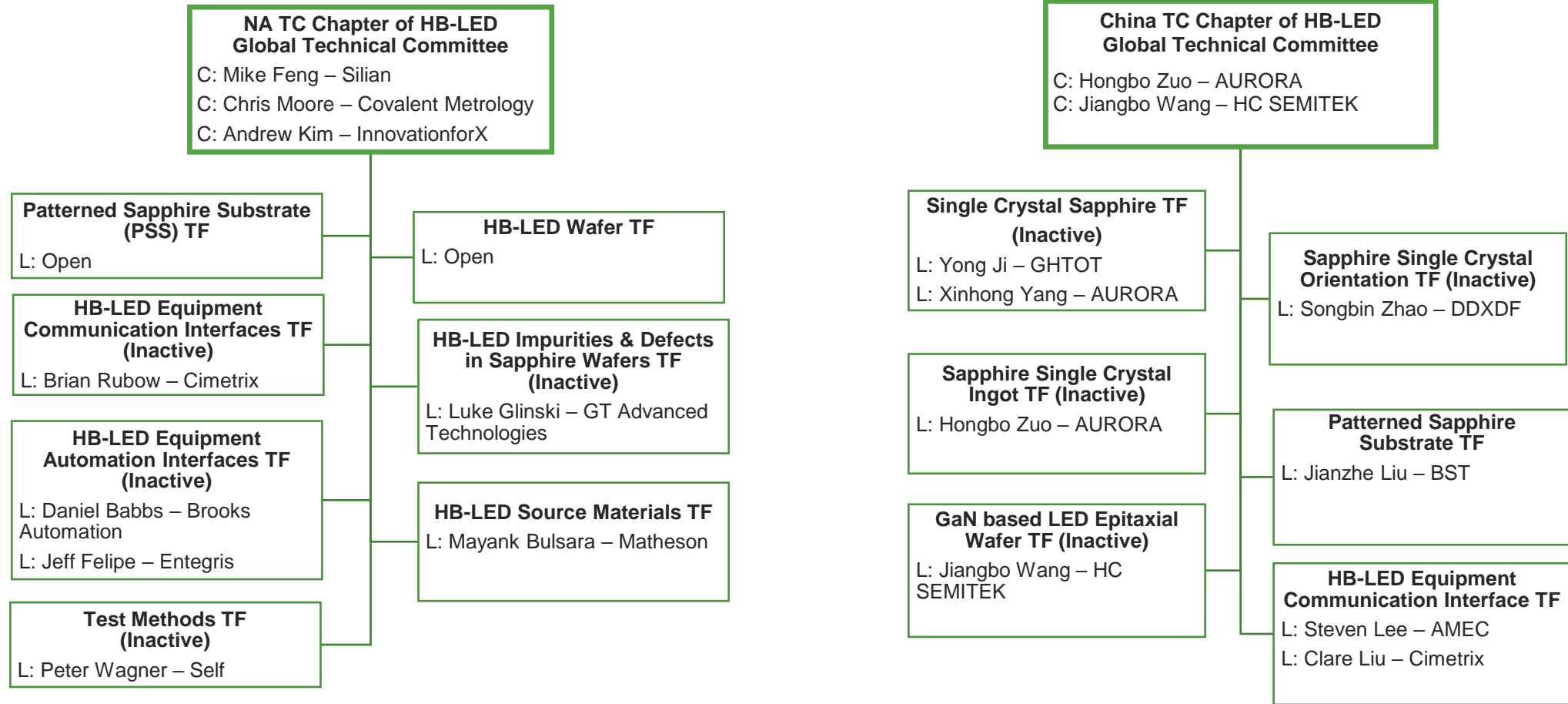
Gases

Global Technical Committee

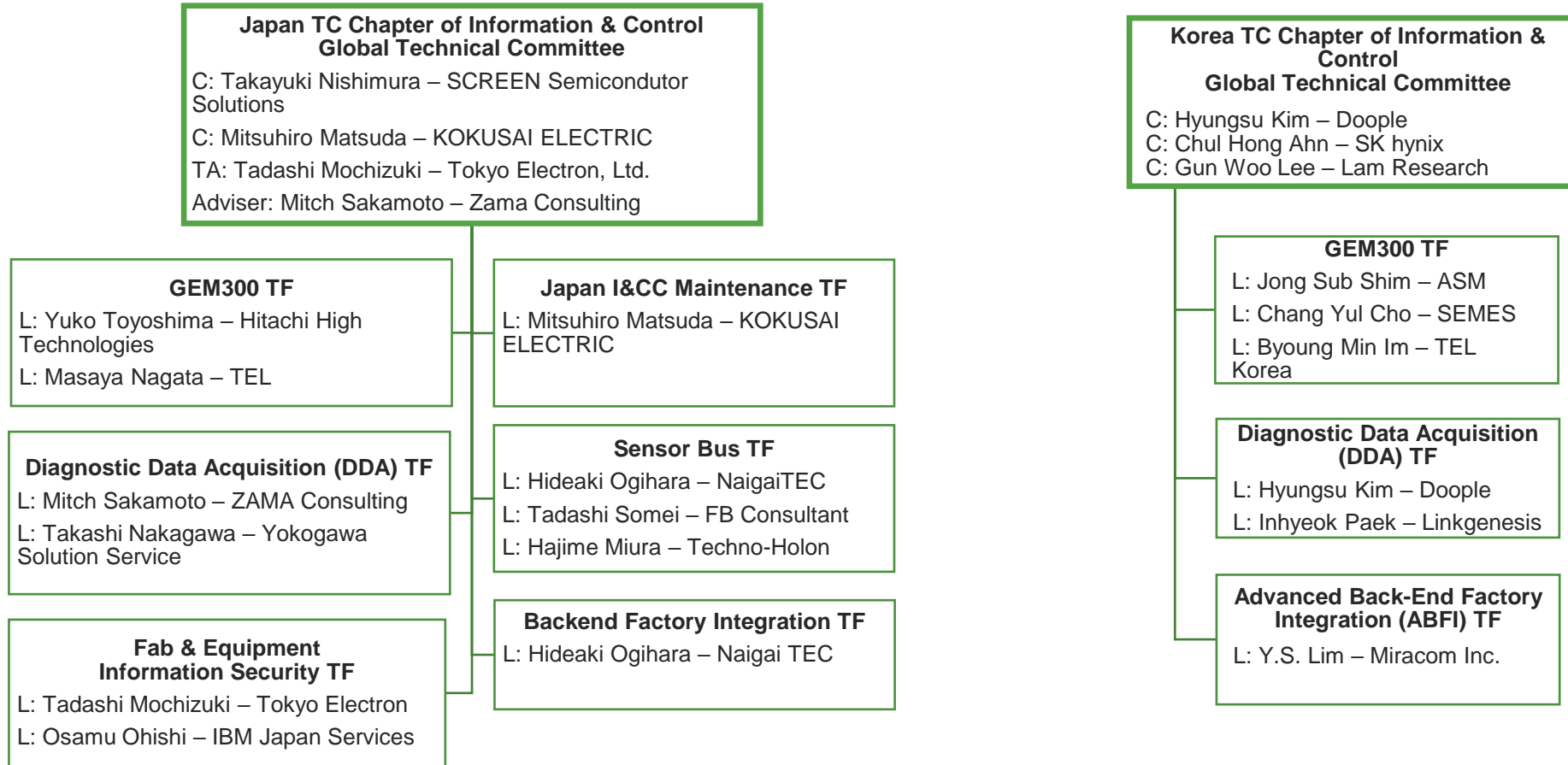


HB-LED

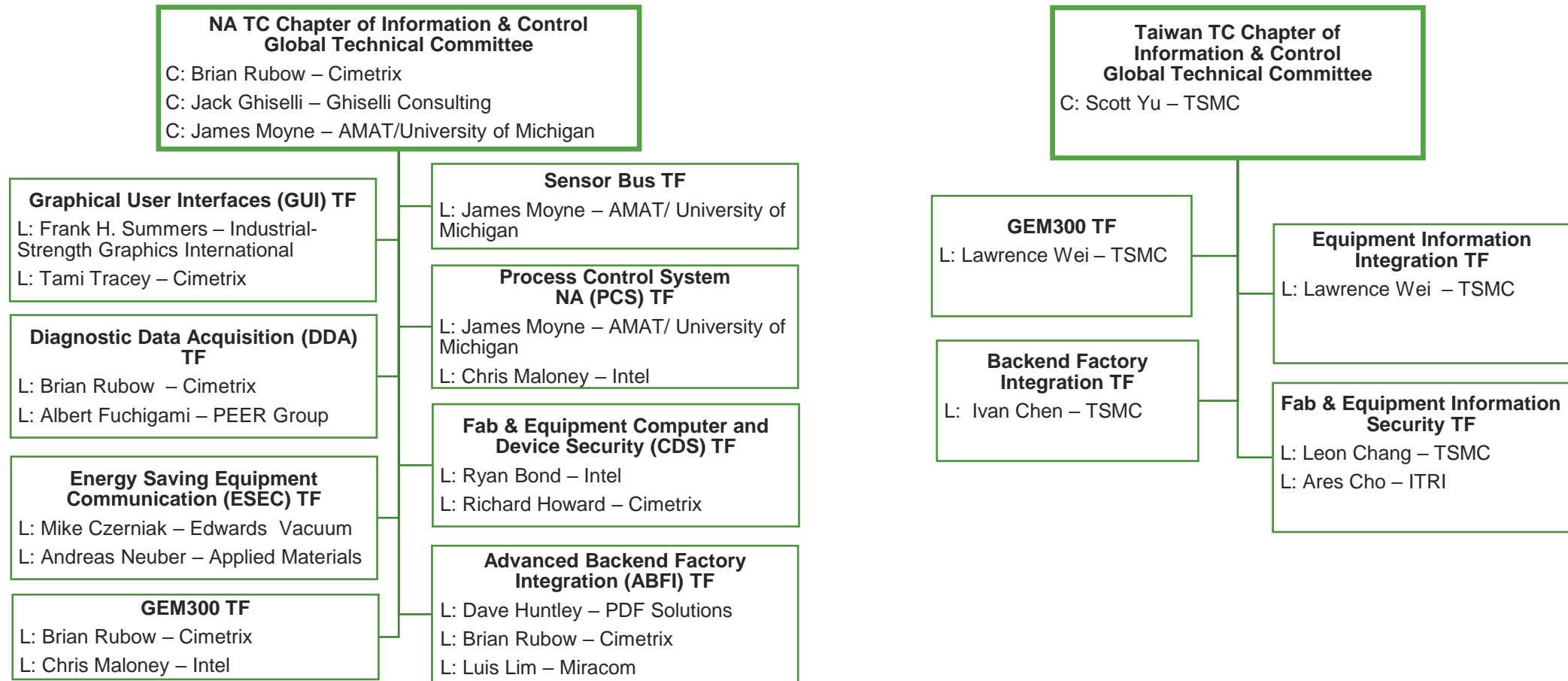
Global Technical Committee



Information & Control (I&C) Global Technical Committee



Information & Control (I&C) Global Technical Committee



Liquid Chemicals

Global Technical Committee



Europe TC Chapter of Liquid Chemicals Global Technical Committee
 C: Jochen Ruth – Pall Corporation

Japan TC Chapter of Liquid Chemicals Global Technical Committee
 C: Hiroshi Tomita – KIOXIA
 C: Hiroyuki Araki – SCREEN Semiconductor Solutions

NA TC Chapter of Liquid Chemicals Global Technical Committee
 C: Don Hadder – Intel
 C: Steve Rogers – KMG Chemicals
 C: Laura Ledenbach – PeroxyChem Evonik
 C: Koh Murai – Mega Fluid Systems

Precursor Specifications TF
 L: Paul Williams – SAFC Hitech

Solvents in Advanced Processes TF
 L: TBD

Liquid Filter TF
 L: Takuya Nagafuchi – Nihon Entegris
 L: Tomoyuki Takakura – Pall

Diaphragm Valve TF
 L: Shigeru Ohsugi – CKD
 L: Kimihito Sasao – Advance Electric

Trace Metal Analysis for High Pure IPA TF
 L: Takuya Nagafuchi – Nihon Entegris
 L: Hiroshi Sugawara – Organo

Liquid-Borne Particle Counter TF
 L: Kaoru Kondo – RION
 L: Kazutoshi Kato – PMS Division/Spectris Co., Ltd.

Welding Fitting TF
 L: Kimihito Sasao – Advance Electric
 L: Takashi Hasegawa – KITZ SCT

Chemical Analytical Methods (CAM) TF
 L: Don Hadder – Intel
 L: David Kandiyeli – Mega Fluid Systems

High Purity Polymer Materials & Components TF
 L: Bob McIntosh – GF Piping

Water Management TF
 L: Paul Kerr – Intel
 L: Slava Libman – FTD Solutions

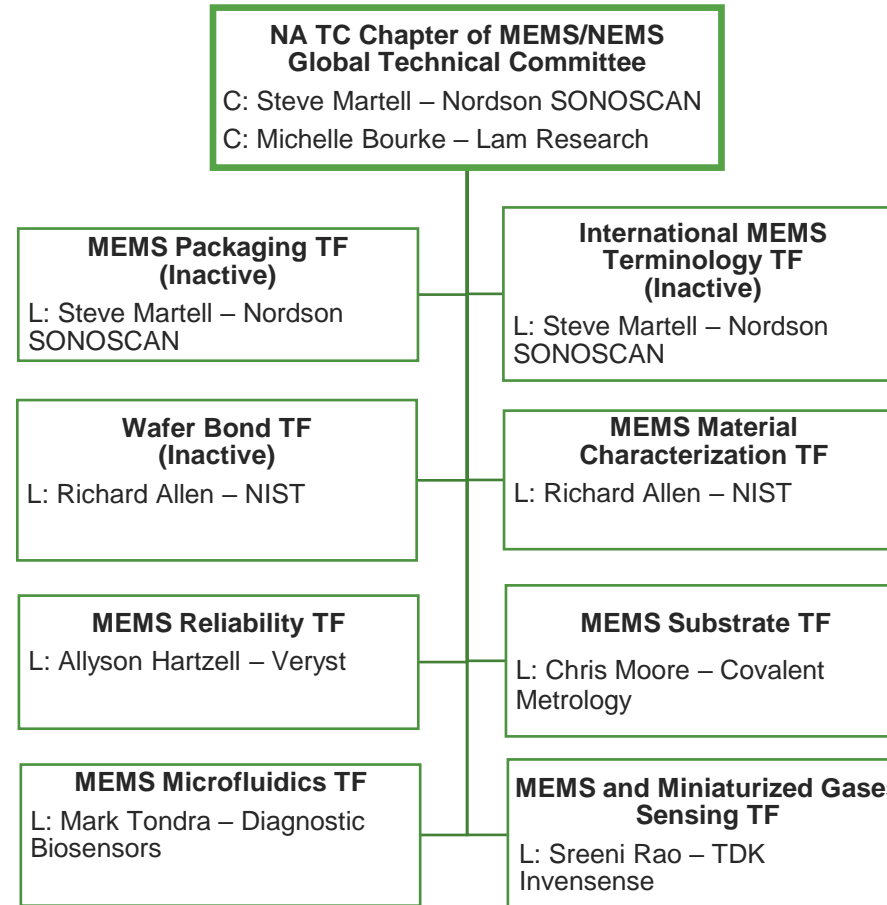
High Purity Liquid Assemblies & Systems TF (Inactive)
 L: Koh Murai – Mega Fluid Systems
 L: David Kandiyeli – Mega Fluid Systems

Ultra Pure Water (UPW) TF
 L: Bonnie Marion – FTD Solutions
 L: Gary van Schooneveld – CT Associates
 L: Bob McIntosh – GF Piping

Chemical Mechanical Planarization Consumables (CMP-C) TF
 L: Alex Tregub – Intel

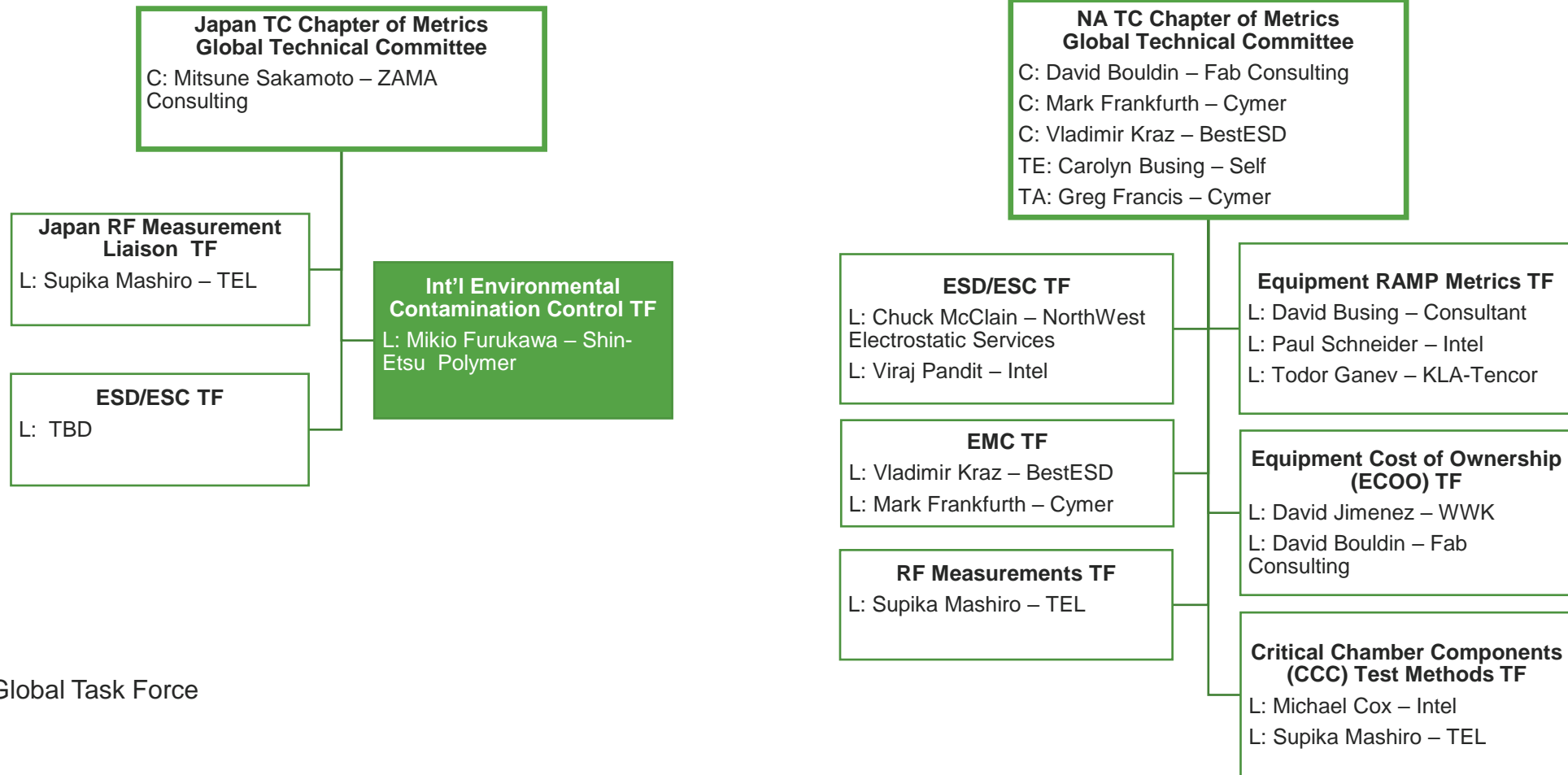
MEMS/NEMS

Global Technical Committee



Metrics

Global Technical Committee

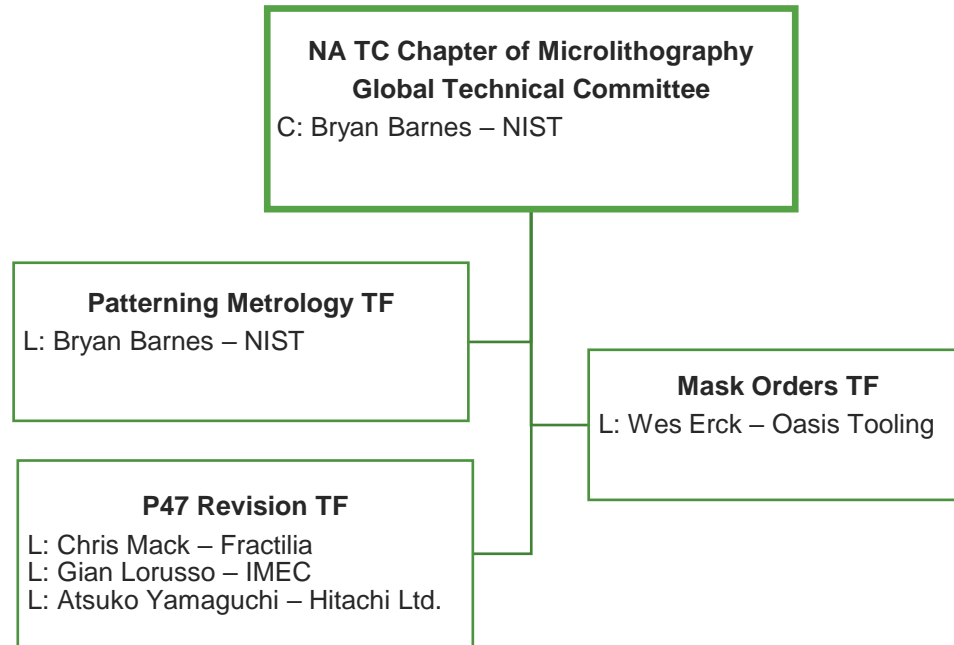


 = Global Task Force

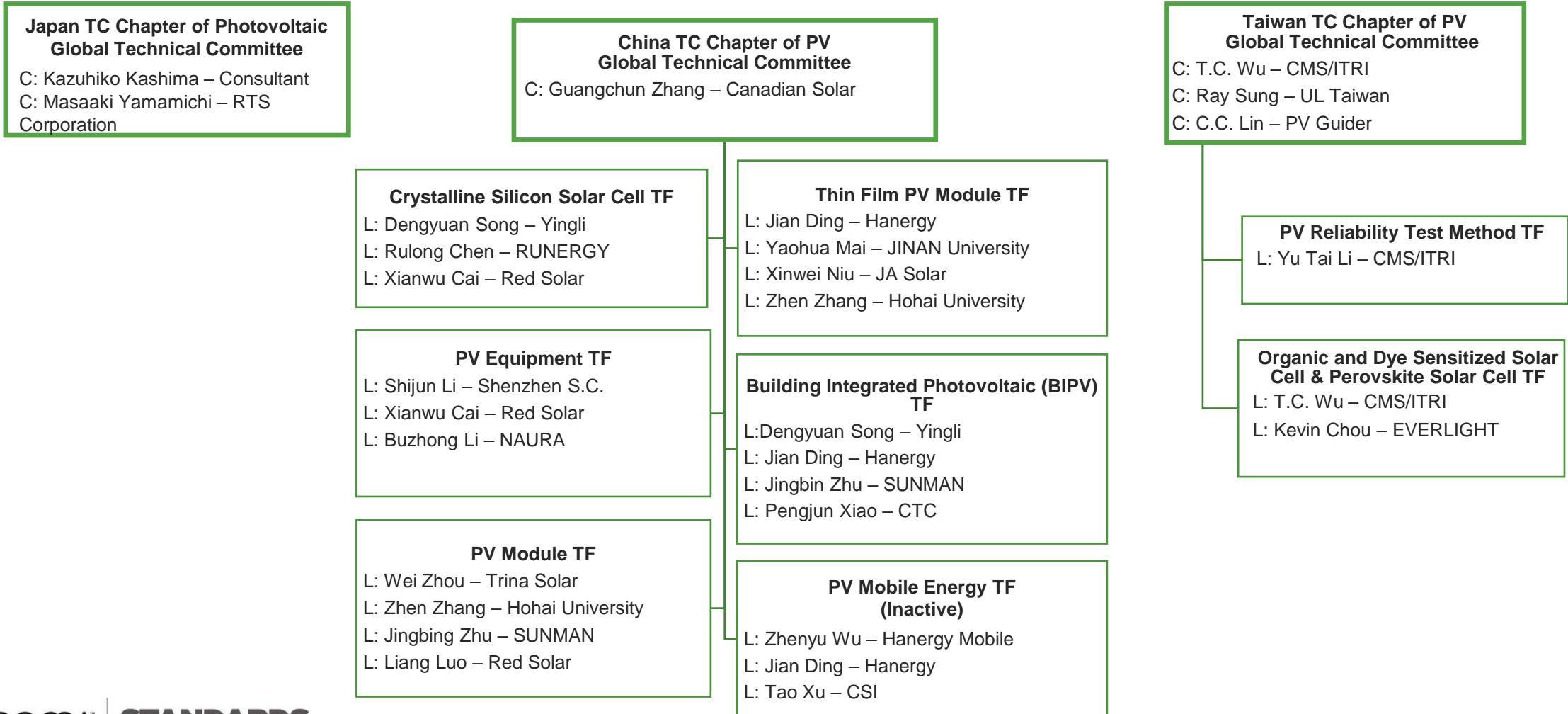


Micropatterning / Microlithography

Global Technical Committee

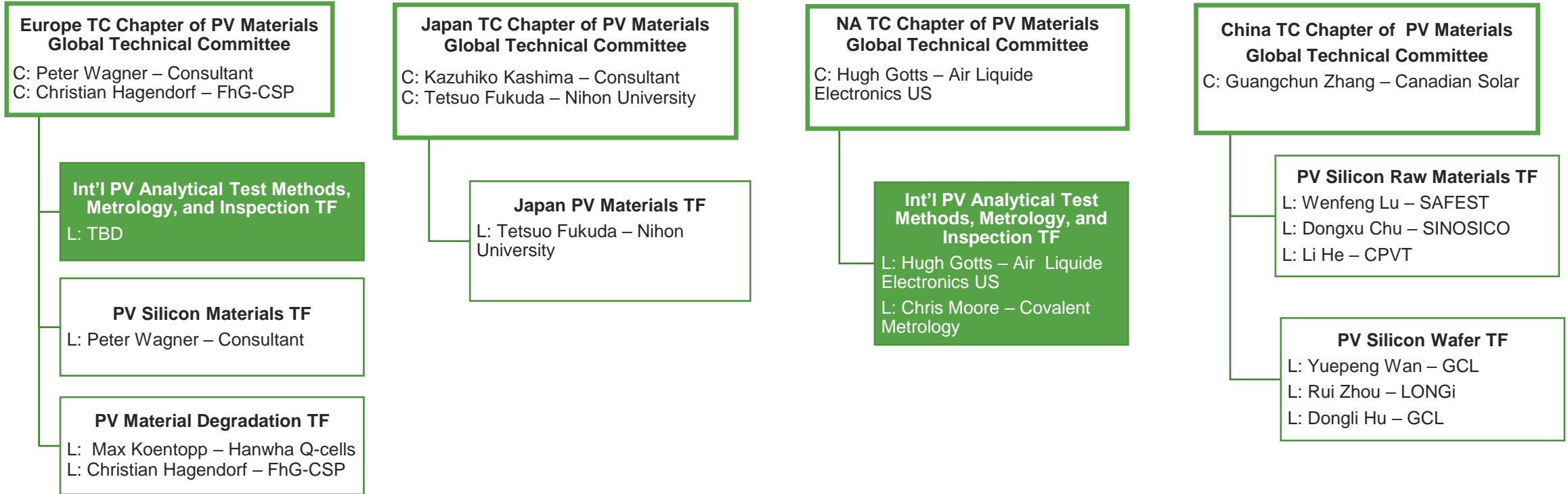



Photovoltaic (PV) Global Technical Committee



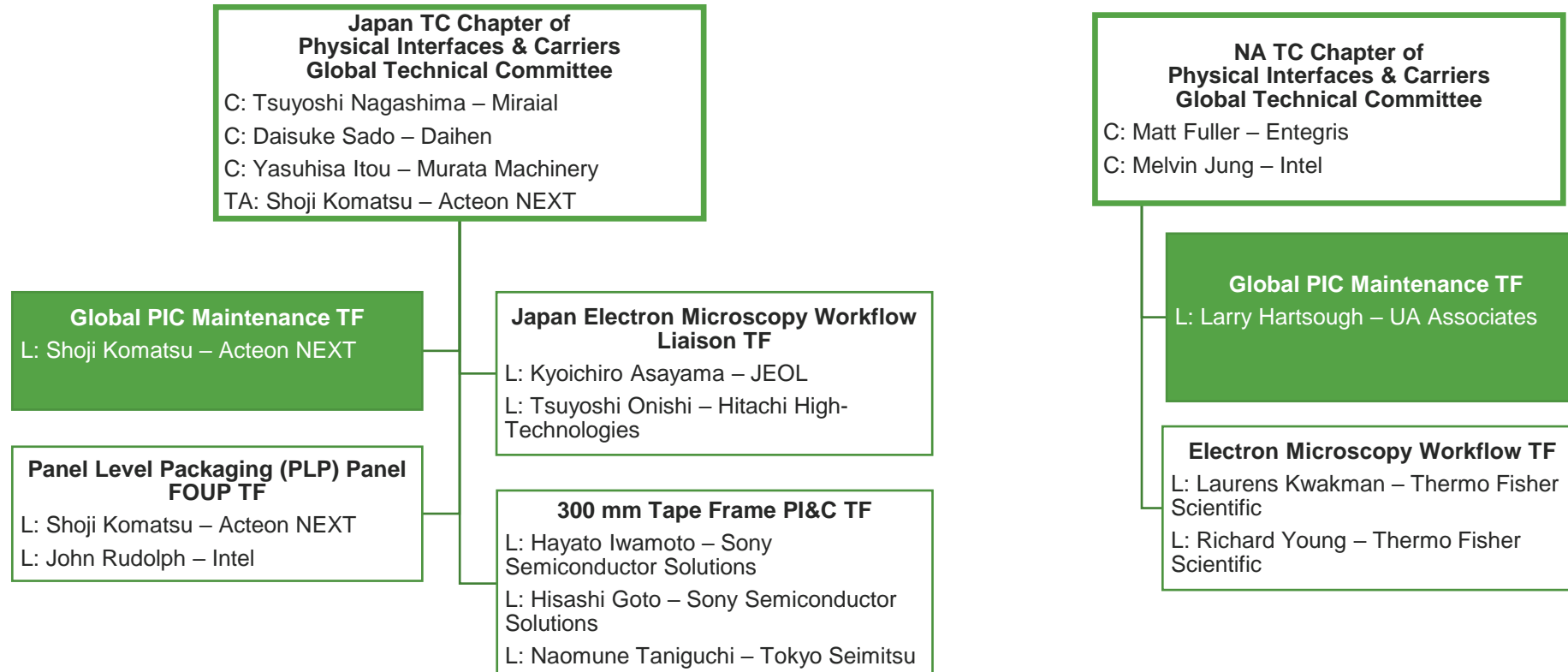
PV Materials

Global Technical Committee



 = Global Task Force

Physical Interfaces & Carriers (PI&C) Global Technical Committee

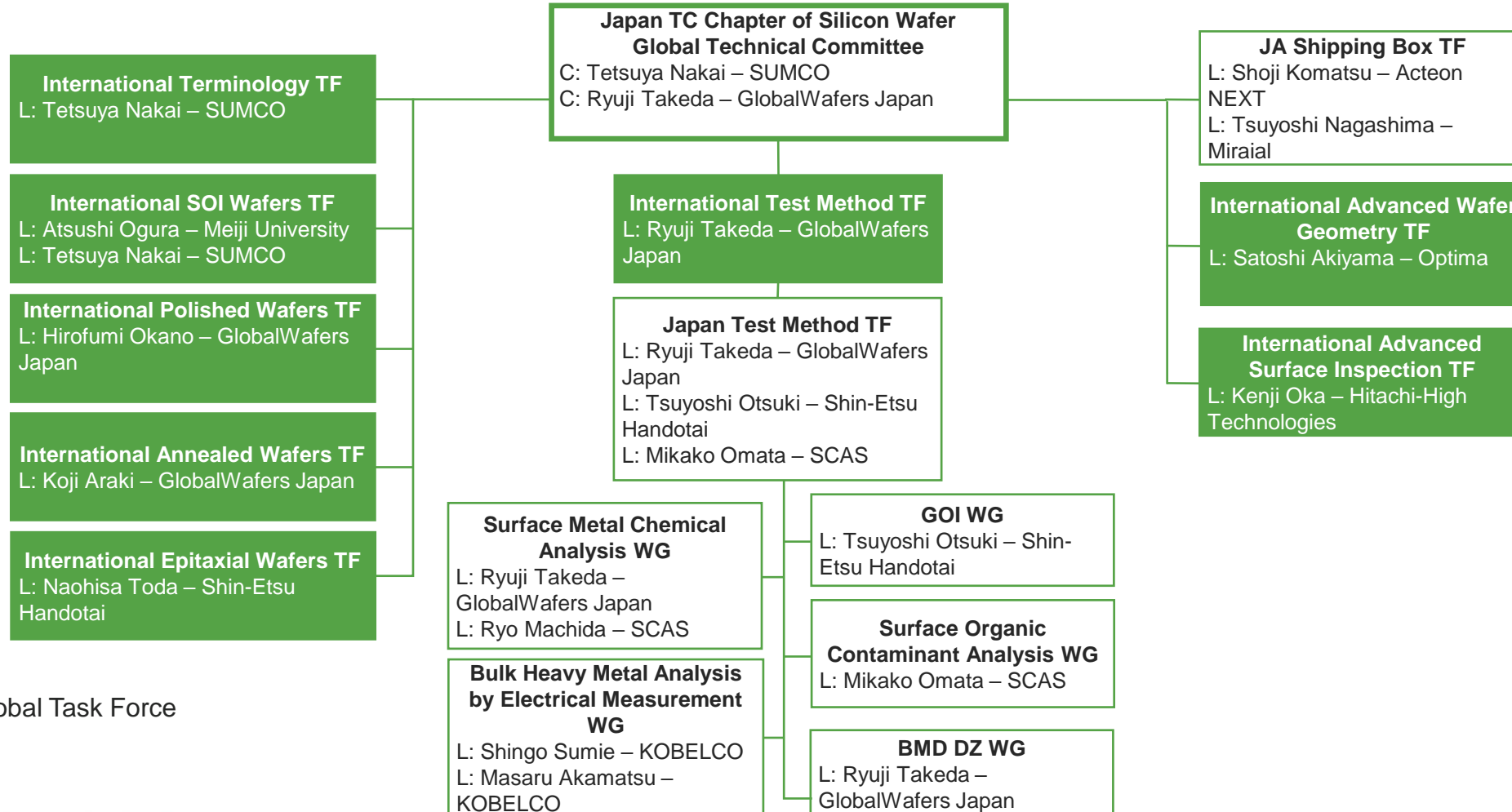


 = Global Task Force

Silicon Wafer Global Technical Committee



Silicon Wafer Global Technical Committee



Traceability

Global Technical Committee

